HD74LS27

Triple 3-input Positive NOR Gates

REJ03D0403–0200
Rev.2.00
Feb.18.2005

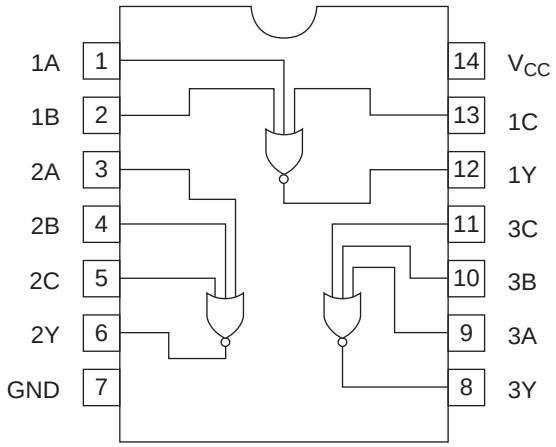
Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS27P	DILP-14 pin	PRDP0014AB-B (DP-14AV)	P	—
HD74LS27FPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)

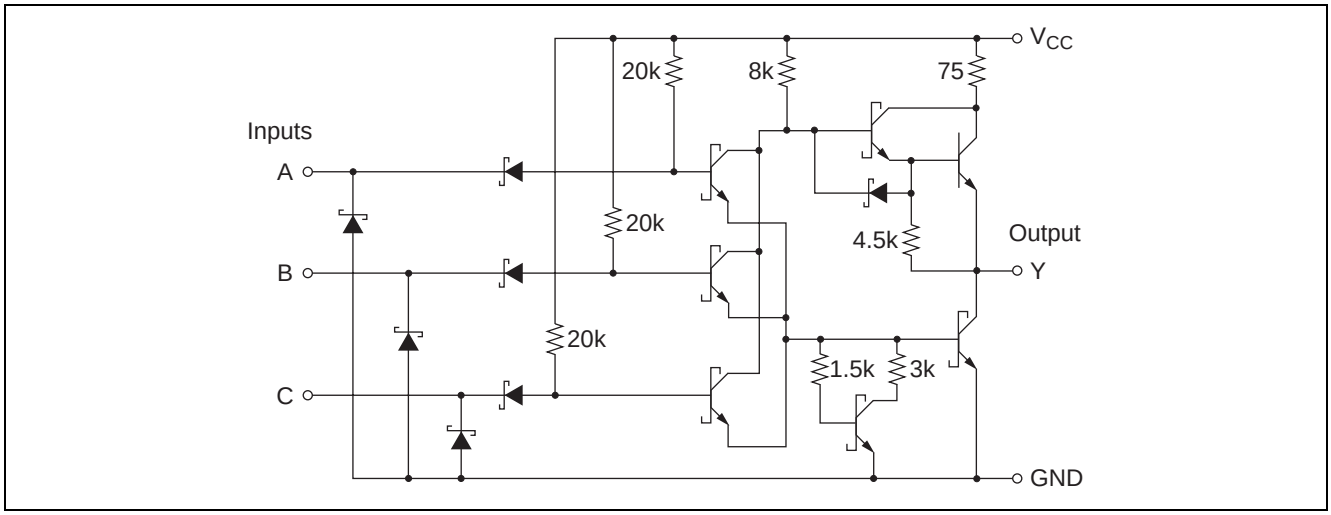
Note: Please consult the sales office for the above package availability.

Pin Arrangement



(Top view)

Circuit Schematic (1/3)



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V_{CC}	7	V
Input voltage	V_{IN}	7	V
Power dissipation	P_T	400	mW
Storage temperature	Tstg	–65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	4.75	5.00	5.25	V
Output current	I_{OH}	—	—	–400	µA
	I_{OL}	—	—	8	mA
Operating temperature	Topr	–20	25	75	°C

Electrical Characteristics

(Ta = –20 to +75 °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V_{IH}	2.0	—	—	V	
	V_{IL}	—	—	0.8	V	
Output voltage	V_{OH}	2.7	—	—	V	V_{CC} = 4.75 V, V_{IL} = 0.8 V, I_{OH} = –400 µA
	V_{OL}	—	—	0.4	V	I_{OL} = 4 mA, V_{CC} = 4.75 V, V_{IH} = 2 V
		—	—	0.5		I_{OL} = 8 mA
Input current	I_{IH}	—	—	20	µA	V_{CC} = 5.25 V, V_I = 2.7 V
	I_{IL}	—	—	–0.4	mA	V_{CC} = 5.25 V, V_I = 0.4 V
	I_I	—	—	0.1	mA	V_{CC} = 5.25 V, V_I = 7 V
Short-circuit output current	I_{OS}	–20	—	–100	mA	V_{CC} = 5.25 V
Supply current	I_{CCH}	—	2.0	4.0	mA	V_{CC} = 5.25 V
	I_{CCL}	—	3.4	6.8	mA	V_{CC} = 5.25 V
Input clamp voltage	V_{IK}	—	—	–1.5	V	V_{CC} = 4.75 V, I_{IN} = –18 mA

Note: * V_{CC} = 5 V, Ta = 25°C

Switching Characteristics

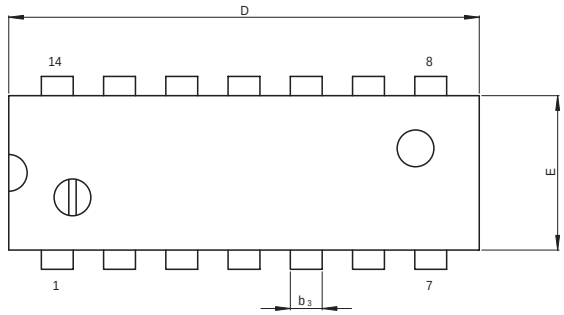
(V_{CC} = 5 V, Ta = 25°C)

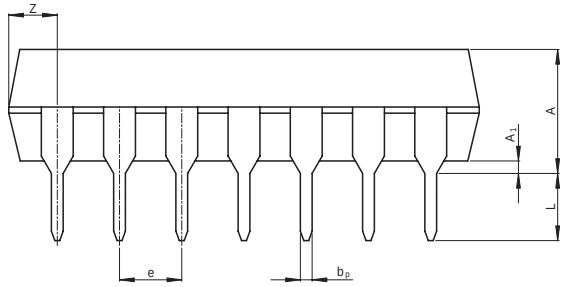
Item	Symbol	min.	typ.	max.	Unit	Condition
Propagation delay time	t_{PLH}	—	10	15	ns	C_L = 15 pF, R_L = 2 kΩ
	t_{PHL}	—	10	15	ns	

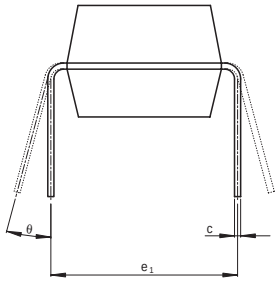
Note: Refer to Test Circuit and Waveform of the Common Item "TTL Common Matter (Document No.: REJ27D0005-0100)".

Package Dimensions

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-DIP14-6.3x19.2-2.54	PRDP0014AB-B	DP-14AV	0.97g



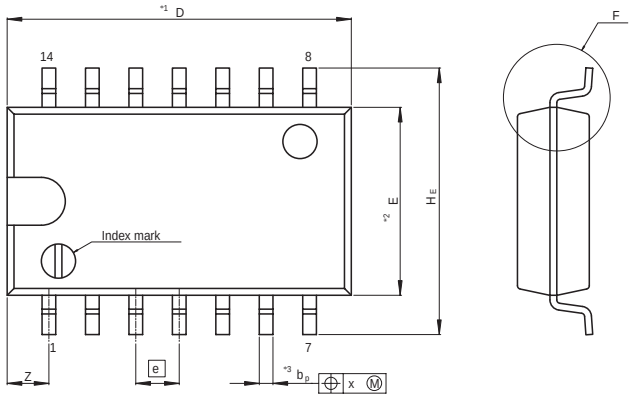


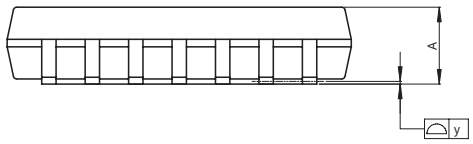


(Ni/Pd/Au plating)

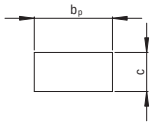
Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
e_1	——	7.62	——
D	——	19.2	20.32
E	——	6.3	7.4
A	——	——	5.06
A_1	0.51	——	——
b_p	0.40	0.48	0.56
b_3	——	1.30	——
c	0.19	0.25	0.31
θ	0°	——	15°
e	2.29	2.54	2.79
Z	——	——	2.39
L	2.54	——	——

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP14-5.5x10.06-1.27	PRSP0014DF-B	FP-14DAV	0.23g

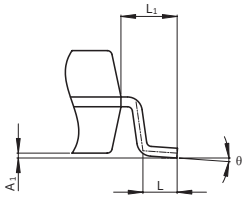




NOTE)
1. DIMENSIONS"*1 (Nom)"AND"*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION"*3"DOES NOT INCLUDE TRIM OFFSET.



Terminal cross section
(Ni/Pd/Au plating)



Detail F

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	——	10.06	10.5
E	——	5.50	——
A_2	——	——	——
A_1	0.00	0.10	0.20
A	——	——	2.20
b_p	0.34	0.40	0.46
b_1	——	——	——
c	0.15	0.20	0.25
c_1	——	——	——
θ	0°	——	8°
H_E	7.50	7.80	8.00
e	——	1.27	——
x	——	——	0.12
y	——	——	0.15
Z	——	——	1.42
L	0.50	0.70	0.90
L_1	——	1.15	——

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